



## **SPECIFICATION**

- Supplier : Samsung electro-mechanics
- Product : Multi-layer Ceramic Capacitor
- Samsung P/N : CL10C221JB8NCNC
- Description : CAP, 220pF, 50V, ±5%, C0G, 0603

A. Samsung Part Number

			<u>CL</u> ①	<u>10</u> ②	<u>C</u> 3	<u>221</u> ④	<u>J</u> (5)	<u>B</u> 6	<u>8</u> 7	<u>N</u> 8	<u>C</u> 9	<u>N</u> 10	<u>C</u> 1	
1 :	Series	Samsung Multi-layer Ceramic Capacitor												
2 :	Size	0603	(inch co	ode)		L:	1.6	± 0.1		mm		W:	0.8 ± 0.1	mm
3	Dielectric	C0G					8	Inne	r ele	ctrod	le		Ni	
4	Capacitance	220	рF					Term	ninat	tion			Cu	
5	Capacitance	±5	%					Plati	ng				Sn 100%	(Pb Free)
1	tolerance						9	Prod	luct				High-Q	
6 I	Rated Voltage	50	V				10	Spec	cial				Reserved fo	r future use
⑦ -	Thickness	0.8	± 0.1	mm			1	Pack	agir	ng			Cardboard T	ype, 7" reel

## B. Samsung Reliablility Test and Judgement condition

	Performance	Test condition						
Capacitance	Within specified tolerance	1₩±10% 0.5~5Vrms						
Q	1000 min							
Insulation	10,000Mohm or 500Mohm ⋅ <i>μ</i> F	Rated Voltage 60~120 sec.						
Resistance	Whichever is Smaller							
Appearance	No abnormal exterior appearance	Microscope (×10)						
Withstanding	No dielectric breakdown or	300% of the rated voltage						
Voltage	mechanical breakdown							
Temperature	COG							
Characterisitcs	(From -55 $^\circ\!\mathrm{C}$ to 125 $^\circ\!\mathrm{C}$ , Capacitance change shoud be within ±30PPM/ $^\circ\!\mathrm{C}$ )							
Adhesive Strength	No peeling shall be occur on the	500g·F, for 10±1 sec.						
of Termination	terminal electrode							
Bending Strength	Capacitance change :	Bending to the limit (1mm)						
	within $\pm 5\%$ or $\pm 0.5_pF$ whichever is larger	with 1.0mm/sec.						
Solderability	More than 75% of terminal surface	SnAg3.0Cu0.5 solder						
	is to be soldered newly	245±5℃, 3±0.3sec.						
		(preheating : 80~120 $^{\circ}$ C for 10~30sec.)						
Resistance to	Capacitance change :	Solder pot : 270±5℃, 10±1sec.						
Soldering heat	within $\pm 2.5\%$ or $\pm 0.25$ pF whichever is larger							
	Tan δ, IR : initial spec.							

	Performance	Test condition				
Vibration Test	Capacitance change :	Amplitude : 1.5mm				
	within $\pm 2.5\%$ or $\pm 0.25_{pF}$ whichever is larger	From 10Hz to 55Hz (return : 1min.)				
	Tan δ, IR : initial spec.	2hours $\times$ 3 direction (x, y, z)				
Moisture	Capacitance change :	With rated voltage				
Resistance	within $\pm 7.5\%$ or $\pm 0.75$ pF whichever is larger	40±2℃, 90~95%RH, 500+12/-0hrs				
	Q : 200 min					
	IR : 500Mohm or 25Mohm $\cdot \mu F$					
	Whichever is Smaller					
High Temperature	Capacitance change :	With 200% of the rated voltage				
Resistance	within $\pm 3\%$ or $\pm 0.3$ pF whichever is larger	Max. operating temperature				
	Q : 350 min	1000+48/-0hrs				
	IR : 1000Mohm or 50Mohm $\cdot \mu F$					
	Whichever is Smaller					
Temperature	Capacitance change :	1 cycle condition				
Cycling	within $\pm 2.5\%$ or $\pm 0.25$ pF whichever is larger	Min. operating temperature $\rightarrow$ 25 °C				
	Tan δ, IR : initial spec.	$\rightarrow$ Max. operating temperature $\rightarrow$ 25 °C				
		5 cycle test				

## C. Recommended Soldering method :

Reflow ( Reflow Peak Temperature : 260+0/-5 °C, 10sec. Max )

\* For the more detail Specification, Please refer to the Samsung MLCC catalogue.